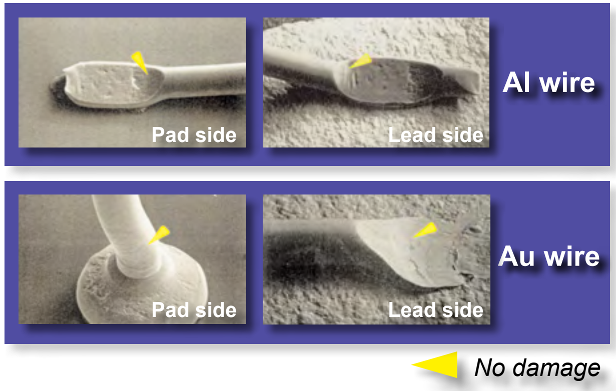
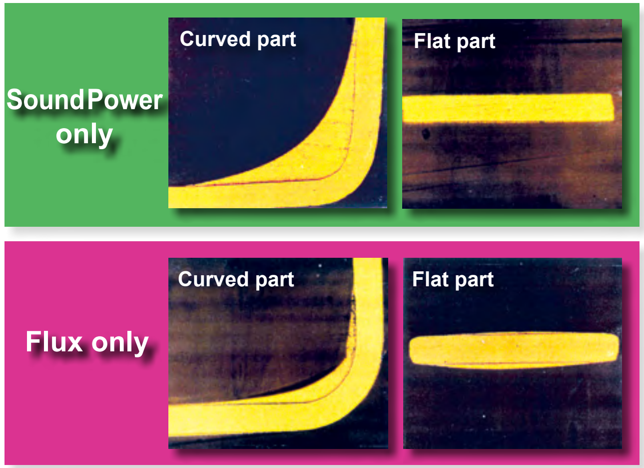
SoundSoldering application

〈半導体 ICパッケージ 音波はんだ付け〉

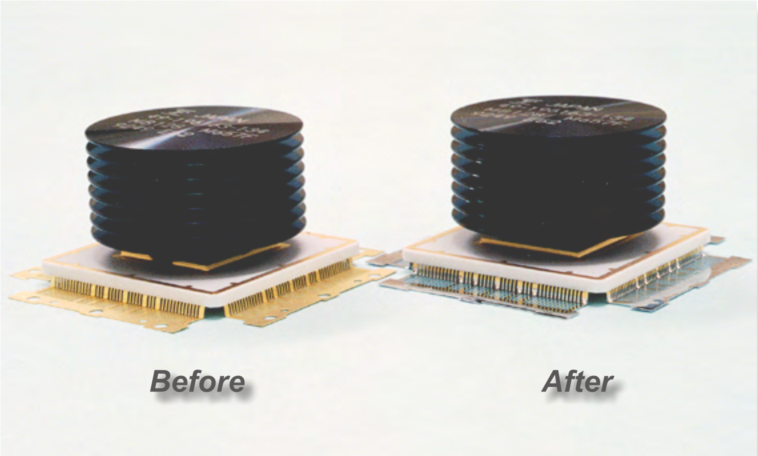
ノンフラックス・サウンドソルダリング



[Bonded wires inside package]



[Cross sections soldered lead frame]



Sound Cavity Soldering System/CSS

QFP type

Advantages ;

1. Non-flux.
2. Pb free.
3. No damage.
4. Beautiful soldered surface.
5. Thin and uniform solder layer.

ULTEX

SoundPower Laboratory